

**IN THE CLAIMS:**

Please cancel/amend/retain the claims as follows:

1. (Currently Amended) A stack chip module including:

a substrate having a predetermined-size groove ~~on one side~~ and a circuit pattern ~~on each side~~, with one end of each circuit pattern being adjacent to a respective ~~the~~ groove, said grooves being arranged on both sides of said substrate in a jig-jag form;

a first semiconductor chip adhered in ~~the~~ each groove of the substrate by adhesive, each of said first semiconductor chips ~~and~~ having a plurality of center pads and a plurality of edge pads, electrically connected to each other, on an upper part thereof;

a plurality of gold wires for electrically connecting ~~the~~ a respective circuit pattern of the substrate and the edge pads of ~~the~~ a respective first semiconductor chip, respectively;

for each of said first semiconductor chips, a second semiconductor chip having a plurality of center pads corresponding to said plurality of center pads on said upper part of the respective first semiconductor chip and ~~the~~ a formative side being opposite to that of the respective first semiconductor chip;

a plurality of bumps interposed between the center pads of the first semiconductor chip chips and the center pads of the corresponding second semiconductor chip chips for joining and electrically connecting said respective center pads; and

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a molding material molding a side of the second semiconductor chips ~~chip~~  
including the gold wires, the edge pads of the first semiconductor ~~chip~~ chips and the circuit  
~~pattern~~ patterns of the substrate.

Claims 2-3 (Canceled).

4. (Original) The stack chip module according to claim 1, wherein the bumps have a  
height of 40 to 100 $\mu$ m.

Claims 5-10 (Canceled).